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(12) **United States Design Patent**
Cook et al.

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(54) **HEAT SINK FOR ELECTRONIC EQUIPMENT**

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(73) Assignee: **Vanner, Inc.**, Hilliard, OH (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/172,402**

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Search** D13/179; 165/80.3, 165/104.14, 104.33, 121, 122, 180, 185; 174/16.3, 52.4; 206/713, 714, 715, 716, 727, 728; 257/706, 707, 718, 719, 720, 721, 722, 727, 686; 361/271, 274.3, 697, 702, 704, 709, 710, 711

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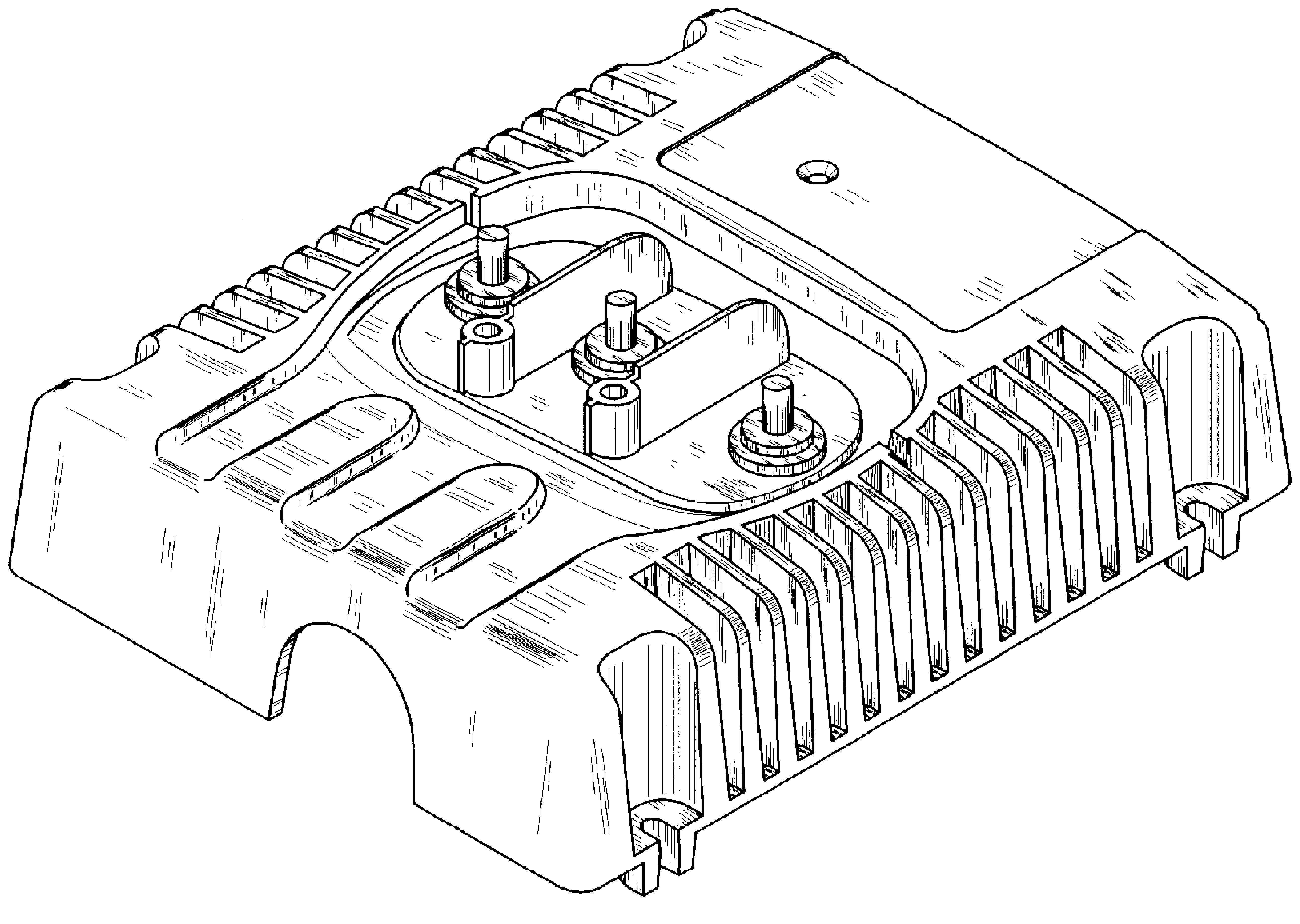
(57) **CLAIM**

The ornamental design for a heat sink for electronic equipment, as shown and described.

DESCRIPTION

FIG. **1** is an isometric view of the heat sink for electronic equipment;
FIG. **2** is a left-side elevational view of the heat sink for electronic equipment;
FIG. **3** is a right-side elevational view of the heat sink for electronic equipment;
FIG. **4** is an elevational view of the aft end of the heat sink for electronic equipment;
FIG. **5** is an elevational view of the forward end of the heat sink for electronic equipment; and,
FIG. **6** is a top plan view of the heat sink for electronic equipment.
The bottom of the heat sink forms no part of the claimed design.

1 Claim, 4 Drawing Sheets



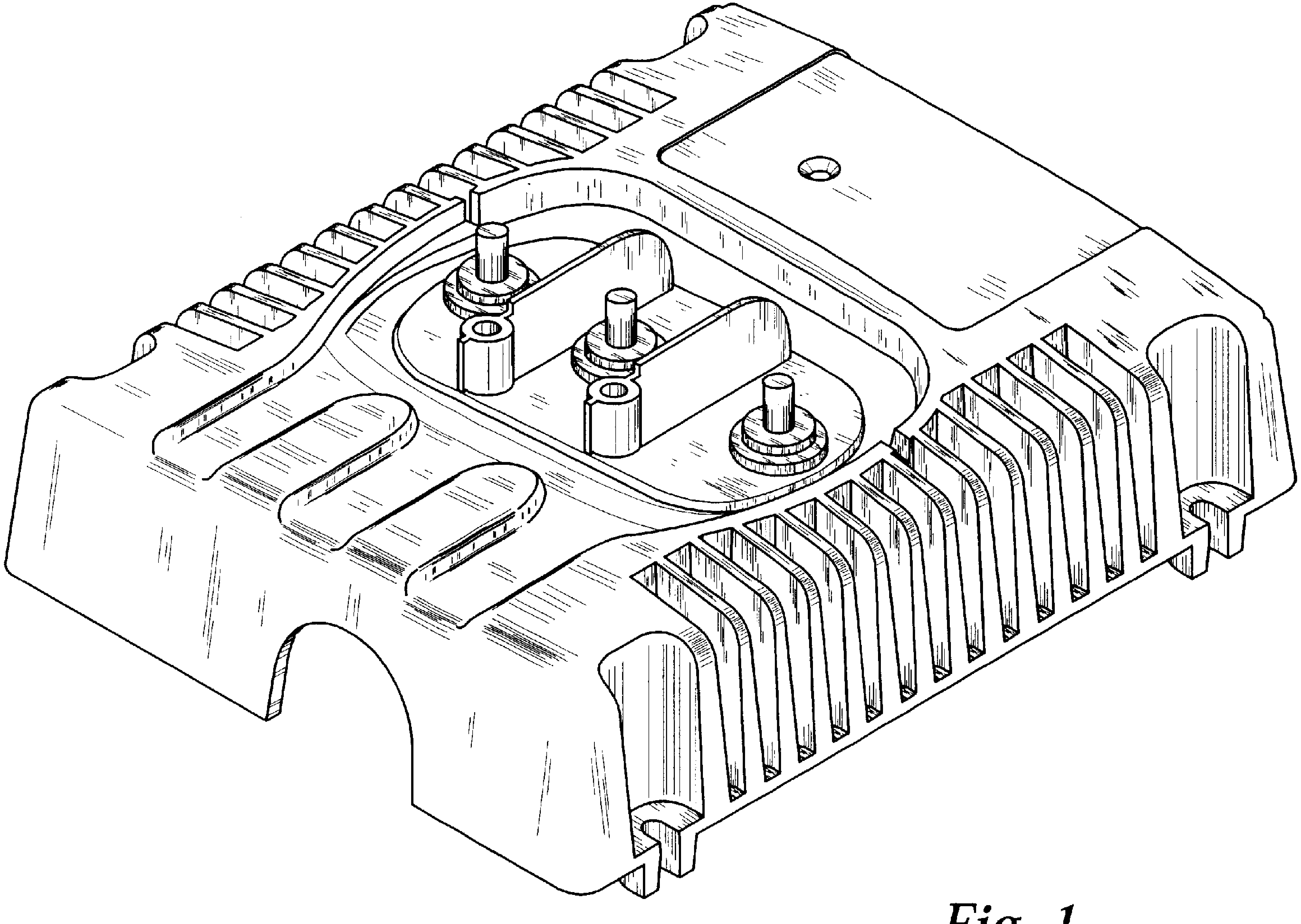


Fig. 1

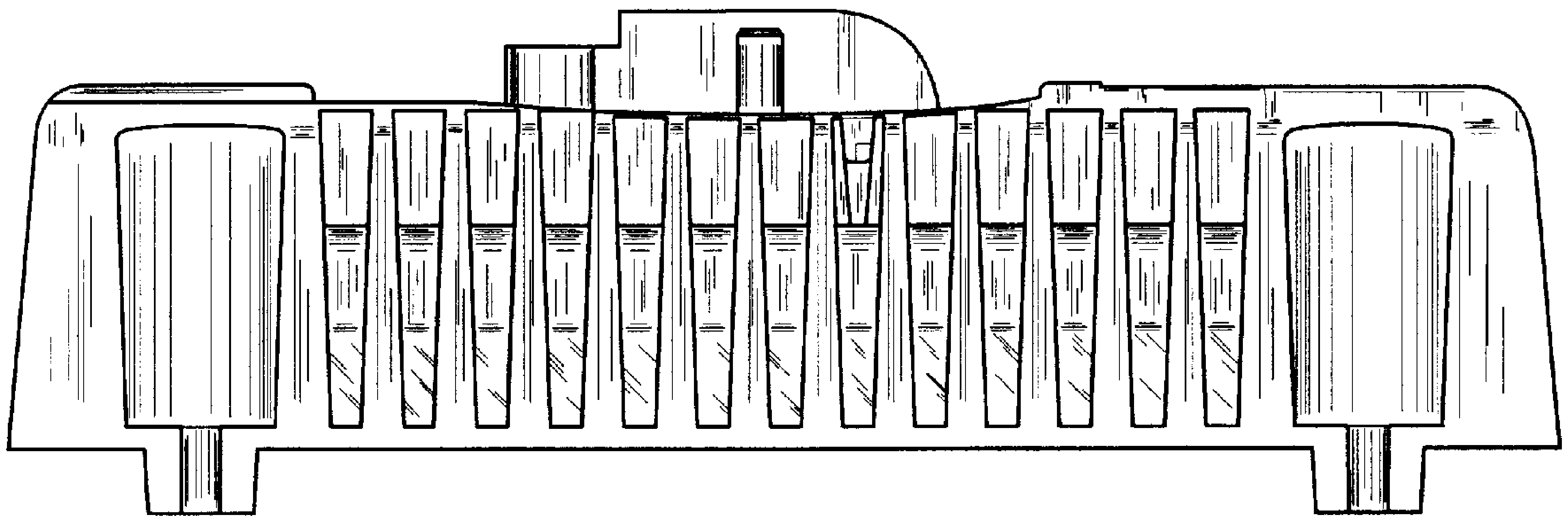


Fig. 2

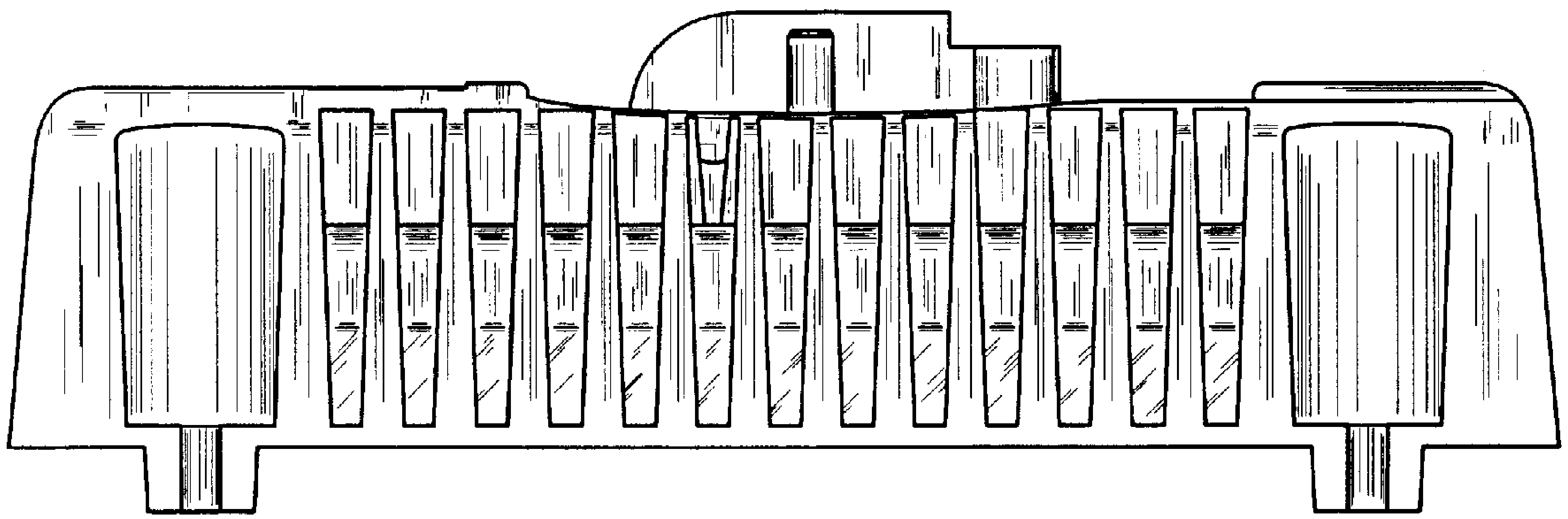


Fig. 3

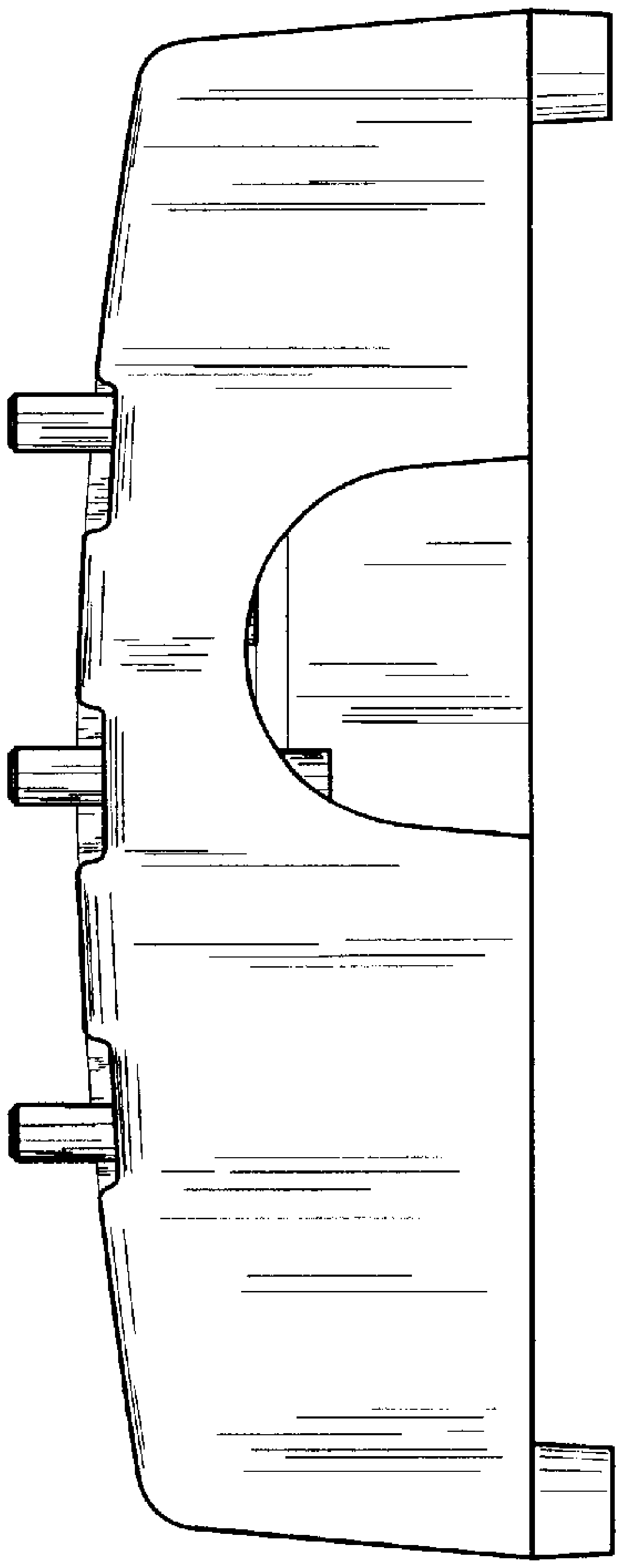


Fig. 4

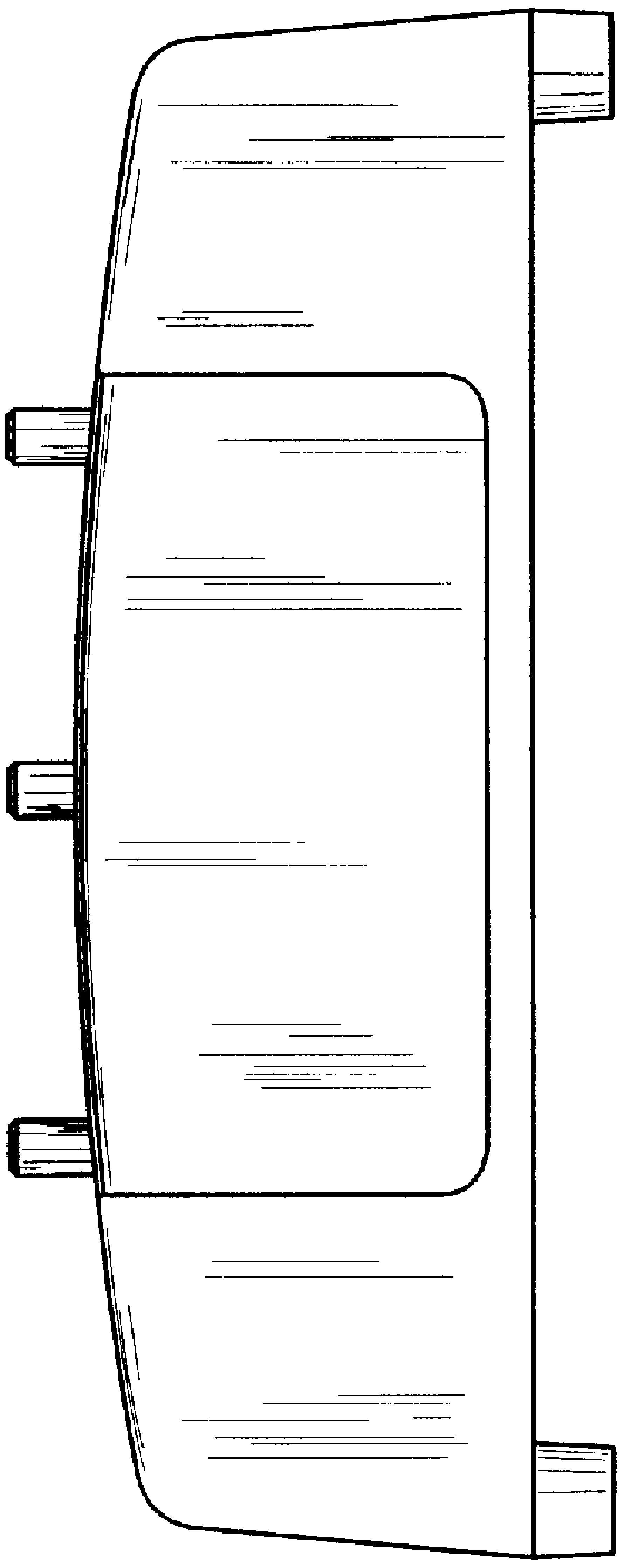


Fig. 5

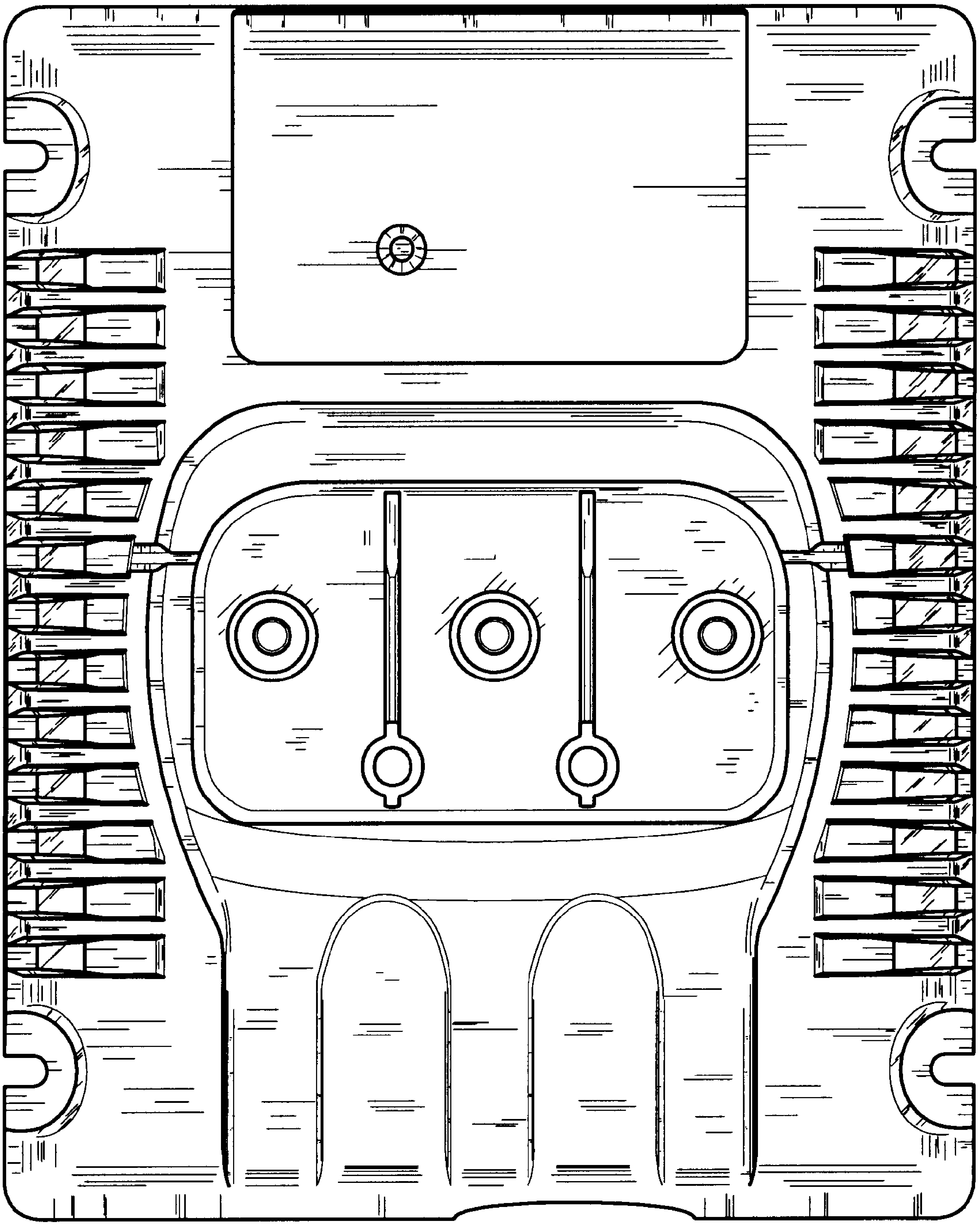


Fig. 6